

ABSTRACT OF THE DISCLOSURE

A method for the packaging of electronic components, comprises the following steps : the mounting of at least one electronic component on its active face side to a base, said base comprising electrical contacts on a first face and connection pads on a second face, and comprising a first series of
5 via holes connecting the electrical contacts and the connection pads and a series of holes; the deposition of a deformable film on the face opposite to the active face of the electronic component or components; the aspiration of the deformable film through the series of holes from the second face of the
10 base, so as to sheath said electronic component or components. The method may furthermore include, on top of the deformable film, a mineral deposition to provide for the hermetic sealing of the components and a conductive deposition to provide for the shielding. Applications : surface acoustic wave filters.

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Figure 2b.

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